

RoHS

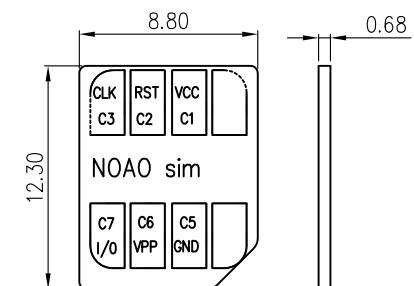
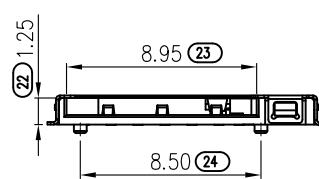
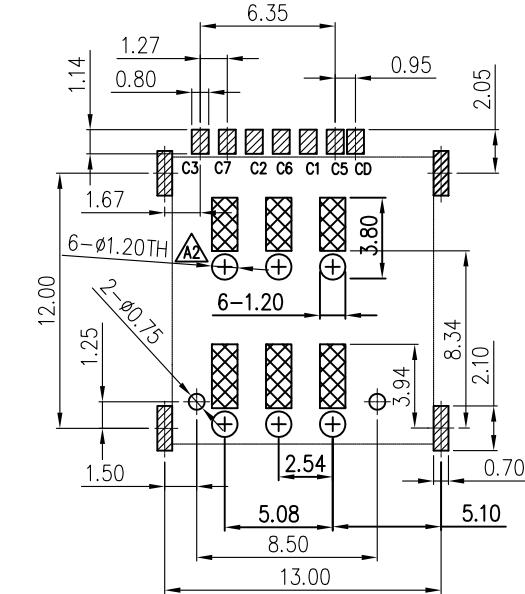
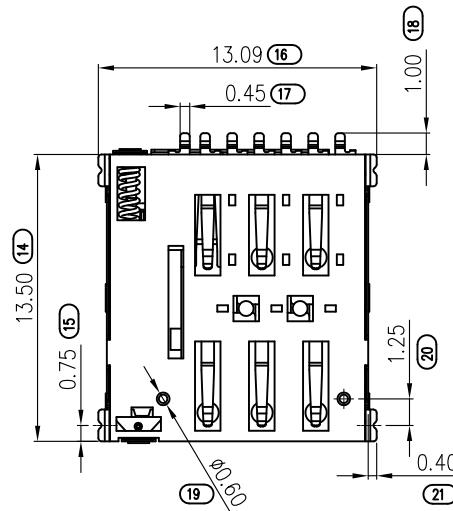
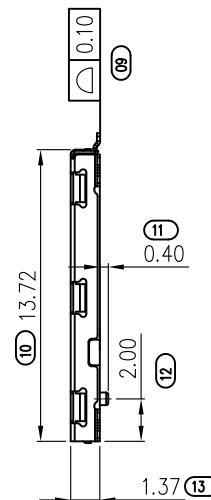
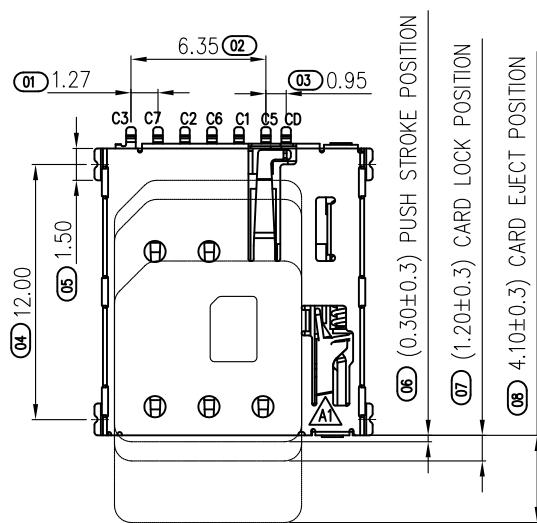
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REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A1	ECN1711006	根据外壳修改变更成品，LAYOUT增加KEEP OUT AREA标示	06/11'17	SUPER	SKY	WZX
A2	ECN171200*	根据客户要求变更	05/12'17	SUPER	SKY	WU



MICRO SIM CARD

NOTES:  
 1) MATERIAL:  
 HOUSING: HI-TEMP. PLASIC UL 94V-0  
 CONTACT: COPPER ALLOY  
 SHELL: STAINLESS STEEL

2). PLATING :  
 TERMINAL:  
 CONTACT AREA: Au GOLD FLASH.  
 SOLDER AREA: AU GOLD FLASH.  
 UNDER PLATE: NICKEL.  
 SHELL: NICKEL PLATED OVER ALL.  
 SOLDER AREA: GOLD FLASH.

3. SPECIALITY:  
 3.1 Rated current:1.0A  
 3.2 Rated voltage:30V  
 3.3 Contact Resistance:50mΩ MAX  
 3.4 Insulation Resistance:1000MΩ MIN 500V DC  
 3.5 Dielectric withstand voltage: 500V AC.  
 3.6 Solder ability:260+0/-5℃, 30±10s.  
 3.7 Durability:5000 Cycles Min.  
 3.8 Operating condition: Temperature:-40℃~+85℃;  
 Humidity 80% R.H MAX

RECOMMENDED PCB LAYOUT  
 GENERAL TOLERANCE ±0.05

PAD  
 KEEP OUT AREA

SIM pin Assignment	MILLIMETERS		UNITS MM	PART NUMBER:	TITLE:
	PIN#	Name	X° ± 2°	X° ±	MAT'L
C1	VCC		.X ± 0.30	.XX ±	SEE NOTES
C2	RST		.XX ± 0.20	.XXX ±	FINISH
C3	CLK		.XXX± 0.10	.XXXX±	SEE NOTES
C5	GND				APPD:
C6	VPP				DWG NO.:
C7	I/O				C-102011612-00
QTY		CHKD:		DR:	
SEE NOTES		1:1		SCALE	1/2
		A2		REV.	

